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Information Disclosure Statement By Applicant	Applicant: My Nguyen	
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U.S. Patent Documents

Foreign Patent or Published Foreign Patent Application

Other Documents

Examiner Initial	No.	Author, Title, Date, Place (e.g. Journal) of Publication
	C1	Goyal, et al, "Failure Mechanism of Brittle Solder Joint Fracture in the Presence of Electroless Nickel Immersion Gold (ENIG) Interface", Proceedings of the 52 nd Electronic Component and Technology Conference, 732-739, May 2002.
	C2	Binary Alloy Phase Diagrams Binary Alloy Phase Diagrams, 2 nd ed, December 1990, T.B.B. Massalski (Editor), L. Kacprzak (Editor), H. Okamoto (Editor), P.R. Subramanian (Editor), pgs 2269, 2642, 2644, 2294, 2996, 1449, 1451, 1746-1748.

Examiner: Initial citation considered. Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.